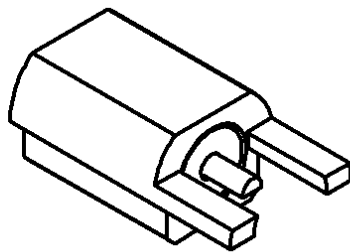
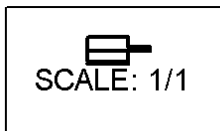
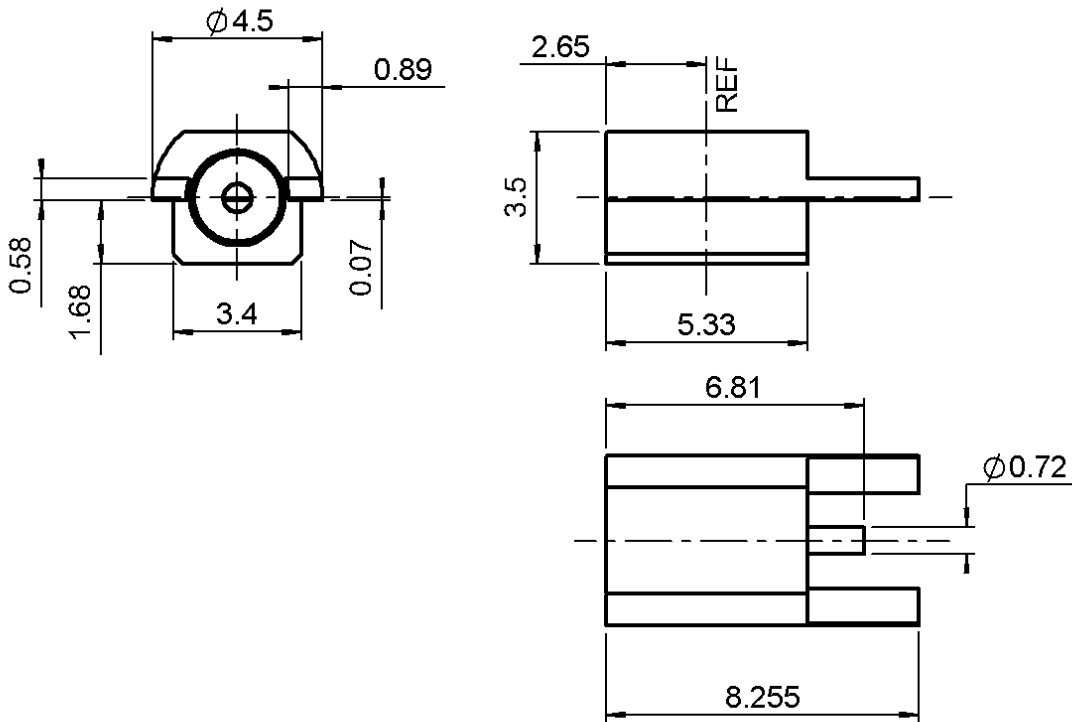


STRAIGHT JACK RECEPTACLE FOR PCB

R110.422.200

SMT TYPE - EDGE CARD

Series : MMCX



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 1.3 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	PTFE	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-
-	-	-

Issue : 0415 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



STRAIGHT JACK RECEPTACLE FOR PCB

R110.422.200

SMT TYPE - EDGE CARD

Series : MMCX

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

672-002905 A0 00

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance		50 Ω
Frequency		0-6 GHz
VSWR	TBD +	0.000 x F(GHz) Maxi
Insertion loss		TBD √F(GHz) dB Maxi
RF leakage	- (- F(GHz)) dB Maxi
Voltage rating		250 Veff Maxi
Dielectric withstanding voltage		500 Veff mini
Insulation resistance		1000 MΩ mini

Operating temperature	-65/+165 ° C
Hermetic seal	NA Atm.cm3/s
Panel leakage	NA

OTHERS CHARACTERISTICS

Assembly instruction

Others :

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	10	N mini
Axial force – Opposite end	10	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	500	Cycles mini
Weight	0.420	g

Issue : 0415 D

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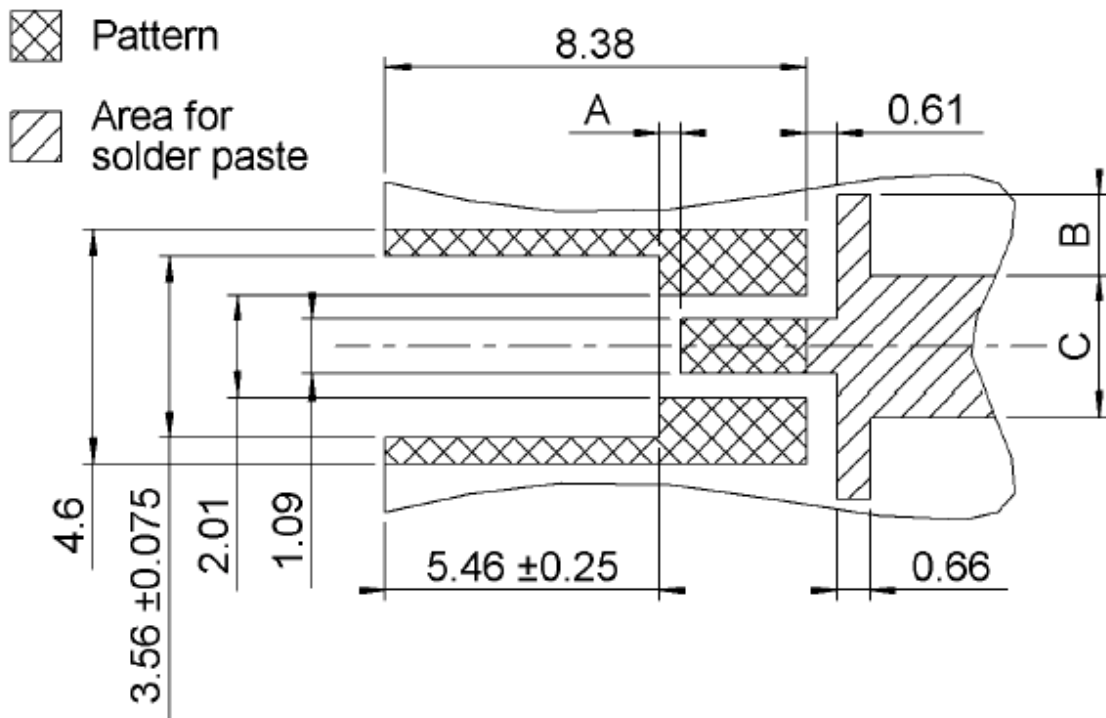
STRAIGHT JACK RECEPTACLE FOR PCB

R110.422.200

SMT TYPE - EDGE CARD

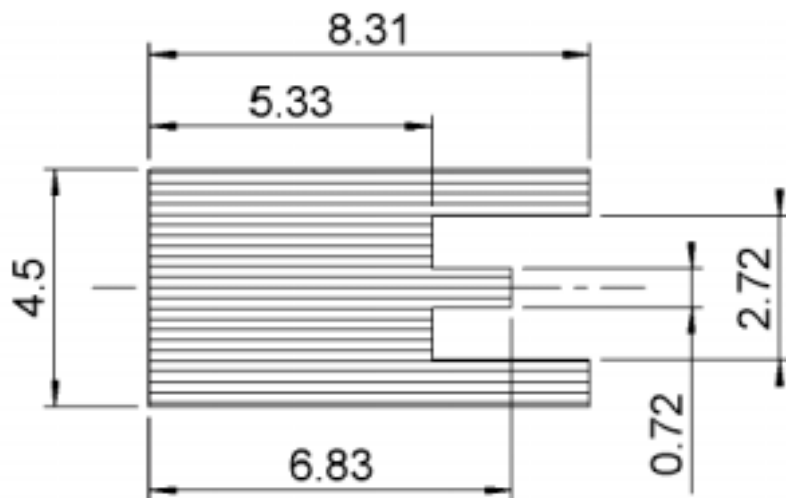
Series : MMCX

PCB PATTERN



PCB THICKNESS	A	B	C
0.79	0.99	-	1.4
0.99	0.89	0.3	1.8
1.6	0.41	1.6	2.79

SHADOW OF MMCX RECEPTACLE FOR VIDEO CAMERA



Issue : 0415 D

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STRAIGHT JACK RECEPTACLE FOR PCB

R110.422.200

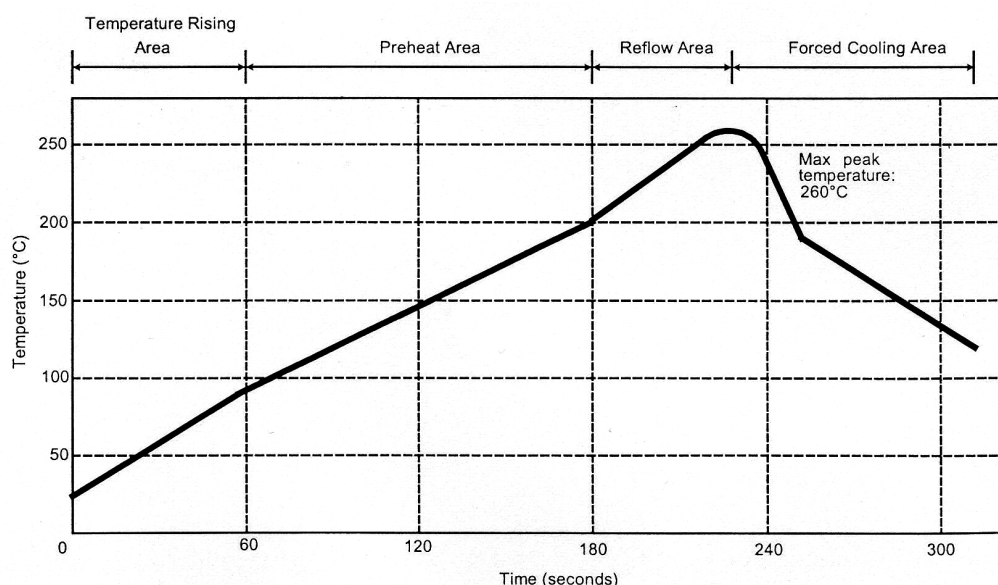
SMT TYPE - EDGE CARD

Series : MMCX

SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micrometers (.0059inches). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is preferred to check the positioning of the component . Adhesive agents are forbidden on the receptacle.
3. Soldering by infrared reflow.
4. Clean printed circuit boards .
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0415 D

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